

DISCLAIMER

* TS3DS10224

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File Description

‘TS3DS10224_tb_windows.sp’ -which is the test bench- invokes other 2 files:

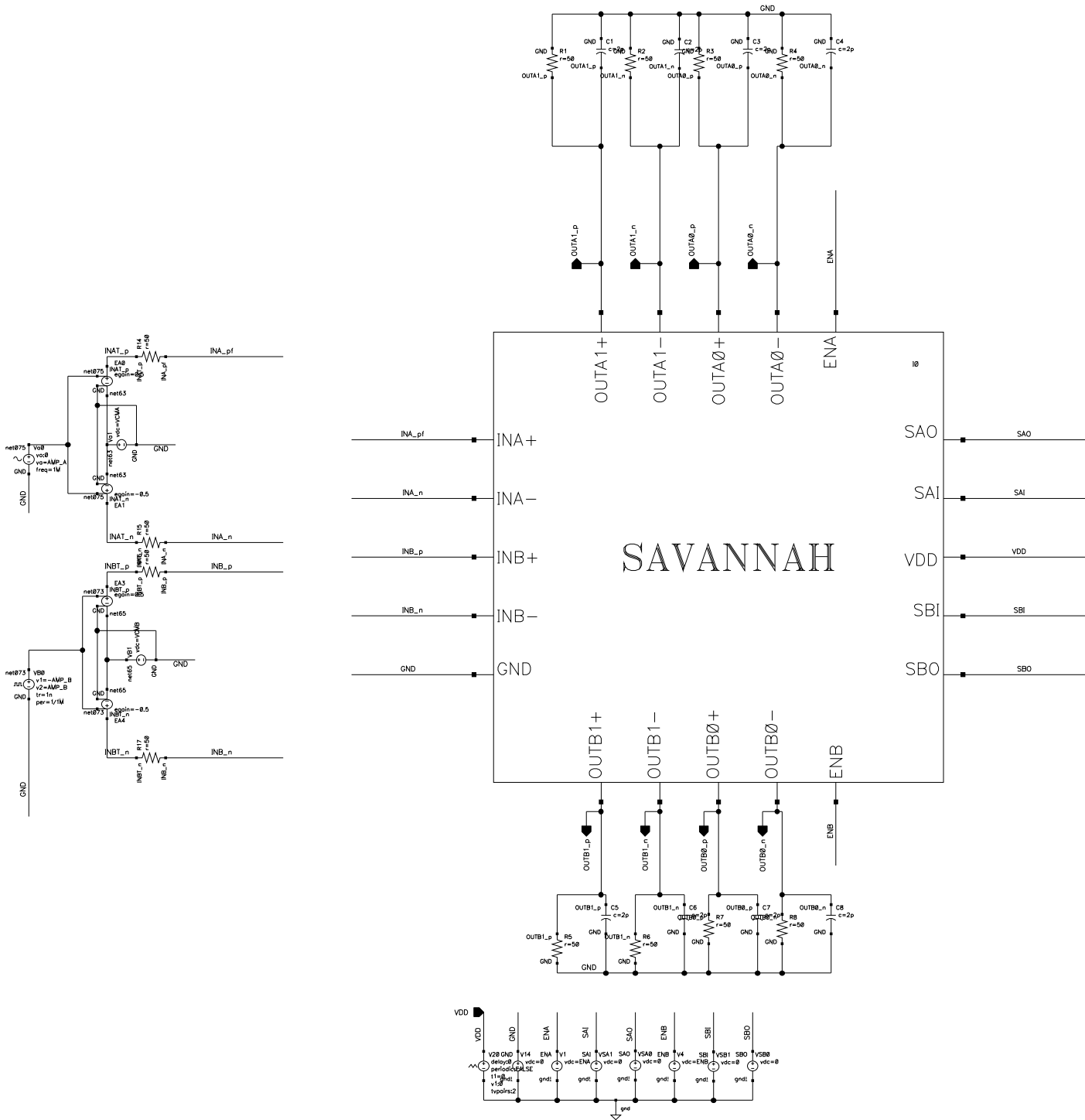
‘TS3DS10224_process_windows.sp’ –nominal process library, and

‘TS3DS10224_ckt_windows.sp’ –subcircuits’ definition.

Instructions

- 1) Open your simulator HSPICE_A-2008.03-SP1 on Windows
- 2) On the file menu, open and run file 'TS3DS10224_tb_windows.sp'.

Plots of the test-setup schematic and simulation results are shown below:



SAVANNAH

